

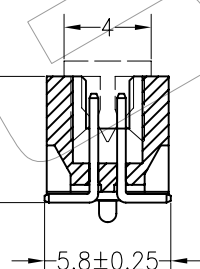
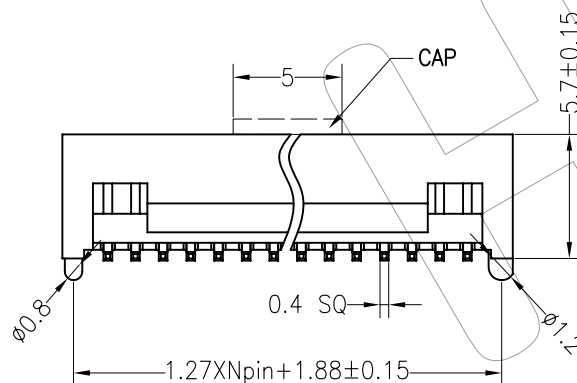
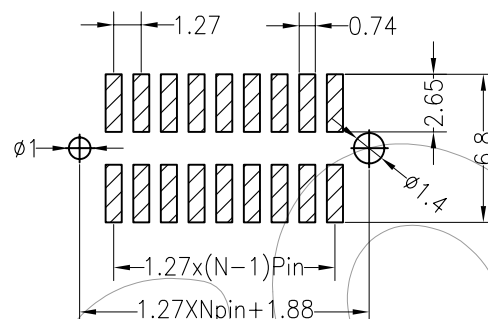
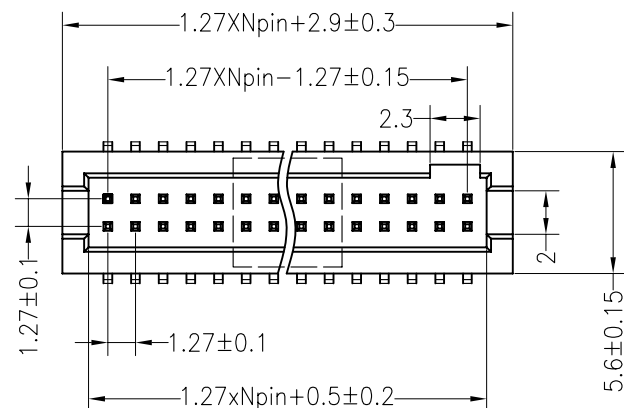
RoHS

Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE ± 0.05)

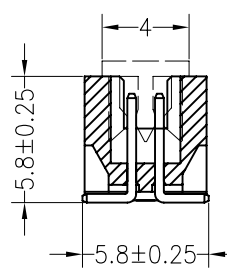
SPECIFICATIONS

Rated Current:1.0AMP
Contact Resistance:20m Ω Max
Withstand Voltage:500V AC/DC
Insulation Resistance:1000M Ω Min
Operation Temperature:-40 $^{\circ}$ c to +105 $^{\circ}$ c

Contact Material:Brass
Contact Plating:Au or Sn Over Ni
Insulator Material:Polyester(UL94V-0)
Standard: PA6T
Max.Processing Temp: 230 $^{\circ}$ C for 30-60 seconds
(260 $^{\circ}$ C for 10 seconds)



TYPE2 With Post



TYPE1 Without Post

Ordering Information

HC-BH732 XX M XX X B K00 X 0X(1,2)

No.of Pins
10-100P

Contact Plating
G0:Gold Flash
G1:3U" Gold
G2:5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
S0:Gold Flash/Tin
SN:Tin

Insulator Material
Option
A=BK-PBT
B=BK-PA66
C=BK-PA6T
D=BK-PA46
E=BK-PA9T
F=BK-LCP

Packing
O=PE Bag
A=Tray
T=Tube
P=Tube+Cap
R=Reel+Cap
M=Reel+Mylar

OPERATION

X.X ± 0.30

X.XX ± 0.20

X.XXX ± 0.10

Angle $\pm 3^{\circ}$

DIM TOL

DRAW

Ayang

SCALE

FIT

UNIT

mm

SIZE

A4

SHEET

1/1

PROJ.

1/1

HECON 东莞市禾康电子有限公司
DONGGUAN HECON ELECTRONICS CO.,LTD

PART NO.

HC-BH732XXMXXB K00X0X(1,2)

TITLE:

1.27mm H5.7 SMT Npin Box Header

A0

REV

DATE

MODIFICATION DESCRIPTION

CHANGE